

AMENDMENTS TO THE CLAIMS

Claim 1. (Currently Amended) A mounting structure of a printed circuit board for establishing electrical connection to a semiconductor package, said mounting structure comprising:

a pad formed on a first surface of said printed circuit board;

a connection wiring formed on a second surface opposite to said first surface;

a plating, said plating covering said pad entirely and extending into a via towards [[to]] the second surface of said printed circuit board; and

the [[a]] via formed through said printed circuit board, said via providing electrical communication between said pad and said connection wiring.

Claim 2. (Previously Presented) A mounting structure as in claim 1, wherein said via has an annular shape on said printed circuit board for establishing said electrical communication.

Claim 3. (Previously Presented) A mounting structure as in claim 1, wherein a plating is provided on the surface of said pad and an inner surface of said via.

Claim 4. (Previously Presented) A mounting structure as in claim 1, wherein said via is formed in said pad of said printed circuit board corresponding to a corner of said semiconductor package.

Claim 5. (Previously Presented) A mounting structure as in claim 1, wherein said via has a truncated cone shape for providing said electrical communication.

Claim 6. (Previously Presented) A mounting structure as in claim 3, wherein said via has a truncated cone shape for providing said electrical communication.

Claim 7. (Previously Presented) A mounting structure as in claim 2, wherein a space is provided between an outer circumference of said pad and a solder resist on said printed circuit board.

Claim 8. (Previously Presented) A mounting structure as in claim 2, wherein a plating is provided on the surface of said pad and an inner surface of said via.

Claim 9. (Previously Presented) A mounting structure as in claim 2, wherein said via has a truncated cone shape for providing said electrical communication.

Claim 10. (Previously Presented) A mounting structure as in claim 8, wherein said via has a truncated cone shape for providing said electrical communication.

Claim 11. (Currently Amended) A mounting structure of a semiconductor package in which a semiconductor package is mounted by soldering on a pad of a printed circuit board for electrical connection with a connection wiring, characterized in that

a via is formed through an entire thickness of said printed circuit board, said pad is integrated with said via on one surface of said printed circuit board,

a plating, said plating covering said pad entirely and extending into [[to]] the via towards the second surface of said printed circuit board;

said pad and said semiconductor package are connected to said via on one surface of said printed circuit board by penetrating a pair into said via or by soldering, and

said connection wiring is connected to said via on the other surface of said printed circuit board.